

(b) a stabilizer extending partially along the length of and on each side of said leadframe leads to improve leadframe planarity[;], [and] said stabilizer including:

(i) a die pad mount integral with and forming a part of said stabilizer disposed beneath said central semiconductor die-receiving region for retaining a semiconductor die thereon.

Amend claim 6 as follows:

6. (Twice Amended) A leadframe stabilizer for use with semiconductor devices, comprising:

(a) an electrically conductive leadframe having a central semiconductor die-receiving region and a plurality of leadframe leads extending outwardly from said central die-receiving region; and

(b) a stabilizer extending partially along the length of and on each side of said lead frame leads to improve leadframe planarity[;], said stabilizer including:

(i) a die pad mount integral with and forming a part of said stabilizer disposed beneath said central semiconductor die-receiving region for retaining a semiconductor die thereon;

(ii) a recess in one surface of said die pad mount; and

(c) a semiconductor die mounted in said recess.

Amend claim 10 as follows:

10. (Twice Amended) A method for stabilizing the leads of a lead frame and providing a semiconductor die mount pad, comprising the steps of:

(a) providing a leadframe having a central semiconductor die-receiving region and a plurality of leadframe leads extending outwardly from said central die-receiving region;

(b) providing a stabilizer, said stabilizer having a die pad integral therewith and disposed beneath said central semiconductor die-receiving region; and

(c) adhering [a] said stabilizer along part of the length and on each side of said leadframe leads to improve leadframe planarity[; and

forming a die pad integral with said stabilizer disposed beneath said central semiconductor die-receiving region].

REMARKS

Claims 1, 6, and 10 have been amended for improved clarity and accuracy.

Claims 1 to 14 remain active in this application.

Claims 1 to 14 were rejected under 35 U.S.C. 102(b) as being anticipated by Hojyo (U.S. 5,559,364). The rejection is respectfully traversed.

Claim 1, from which claims 2 and 5 depend, requires, among other features, a stabilizer extending partially along the length of and on each side of the leadframe leads, the stabilizer also including a die pad mount integral with and forming a part of the stabilizer disposed beneath the central semiconductor die-receiving region for retaining a semiconductor die thereon. No such structure is taught or suggested by Hojyo.

Claim 2 further limits claim 1 by requiring that the stabilizer be made of an insulating material. No such combination is taught or suggested by Hojyo.

Claim 5 further limits claim 1 by requiring that the die pad mount have a recess in one surface into which a semiconductor die is mounted. It is respectfully submitted that